

A Fast Wafer-Level Spatial Variation Modeling Algorithm for Test Cost Reduction of Analog/RF Circuits

Hugo Gonçalves^{1,2}, Xin Li¹, Miguel Correia² and Vitor Tavares²

¹ECE Department, Carnegie Mellon University, USA

²Faculdade de Engenharia, Universidade do Porto, Portugal

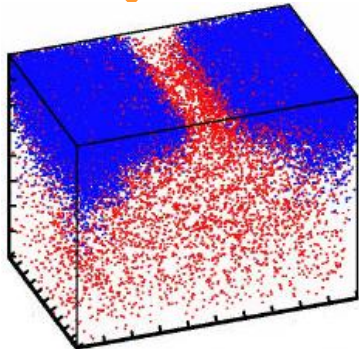
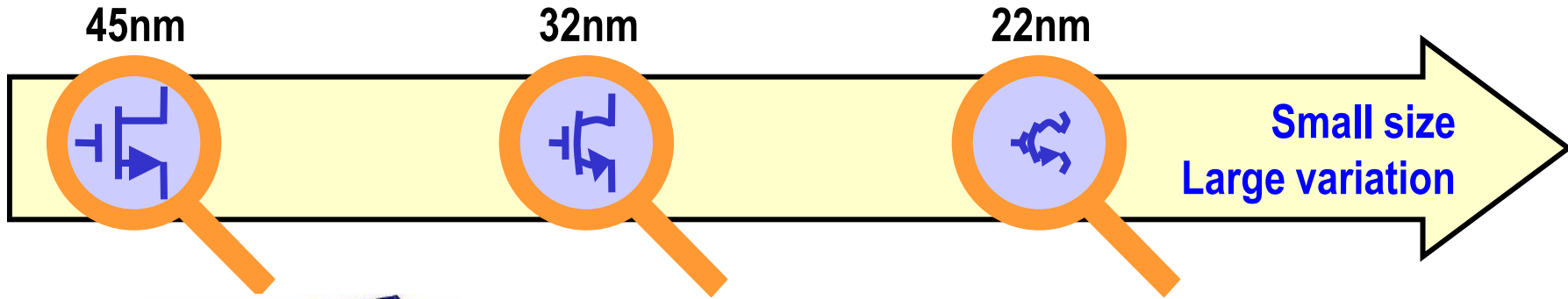


09/07/2014

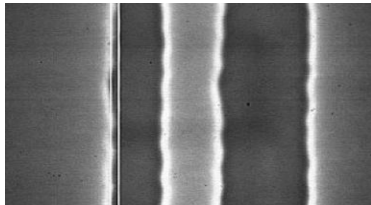
Outline

- **Motivation and background**
 - ▼ Virtual probe (VP)
- **Proposed approach**
 - ▼ Dual Augmented Lagrangian method (DALM)
 - ▼ Two-pass test flow
- **Experimental results**
- **Conclusions**

Process Variation



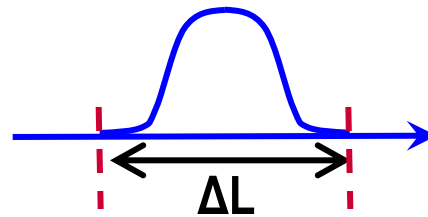
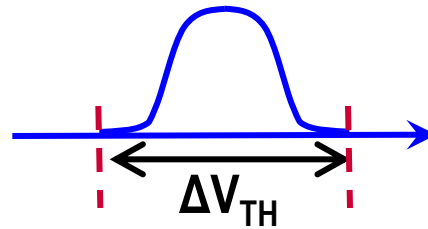
Doping fluctuation



Line edge roughness

$$V_{TH} = \bar{V}_{TH} + \Delta V_{TH}$$

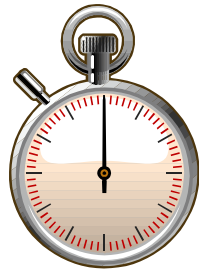
$$L = \bar{L} + \Delta L$$



Parametric variations

Wafer Probe Test

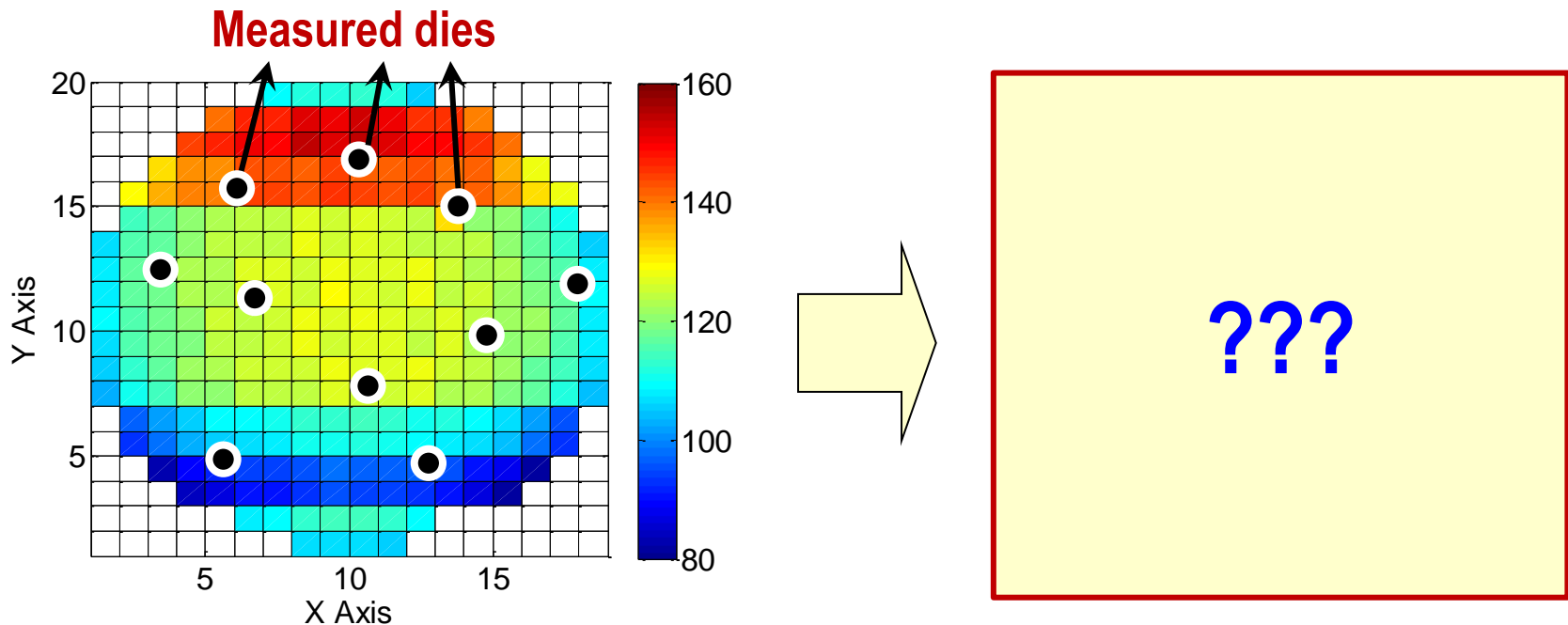
- Multiple test items must be measured for each die
- An industrial example of dual radio RF transceiver
 - ▼ ~1 second testing time per die
 - ▼ ~6500 dies per wafer
 - ▼ ~ 2 hour testing time per wafer
- Measuring all test items is time-consuming



~2h per wafer

Test Cost Reduction by Spatial Variation Modeling

- Measure a small number of dies at selected spatial locations
- Recover the full wafer map by statistical algorithm



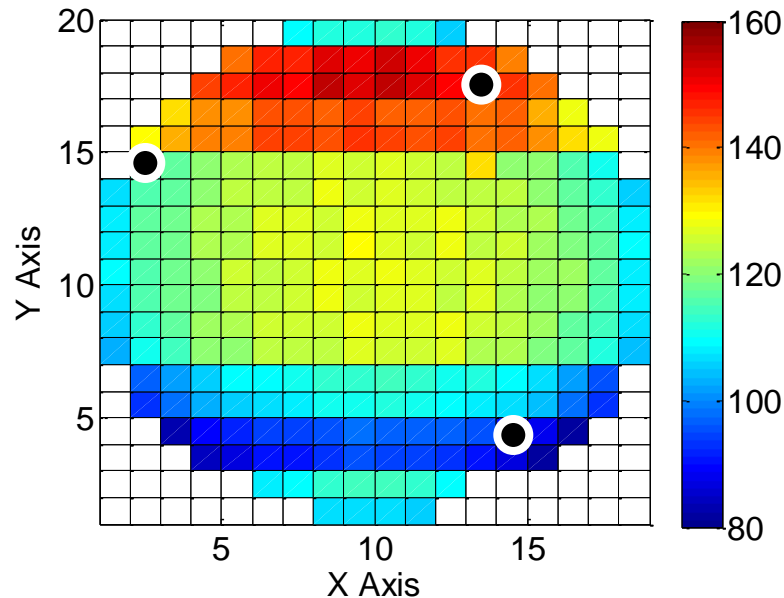
Measured delay values (normalized)
from 282 industrial chips

Recovered wafer
map

- [Chang11], [Kupp12], [Huang13], [Hsu13], etc.

Virtual Probe (VP)

- List a set of linear equations based on measurement data



Measured delay values (normalized)
from 282 industrial chips

$$\begin{bmatrix} \times \\ \times \\ \times \end{bmatrix} = \begin{bmatrix} \times & \times & \times & \times & \times \\ \times & \times & \times & \times & \times \\ \times & \times & \times & \times & \times \end{bmatrix} \cdot \begin{bmatrix} \times \\ \times \\ \times \\ \times \\ \times \end{bmatrix}$$

DCT basis function

Performance measurement

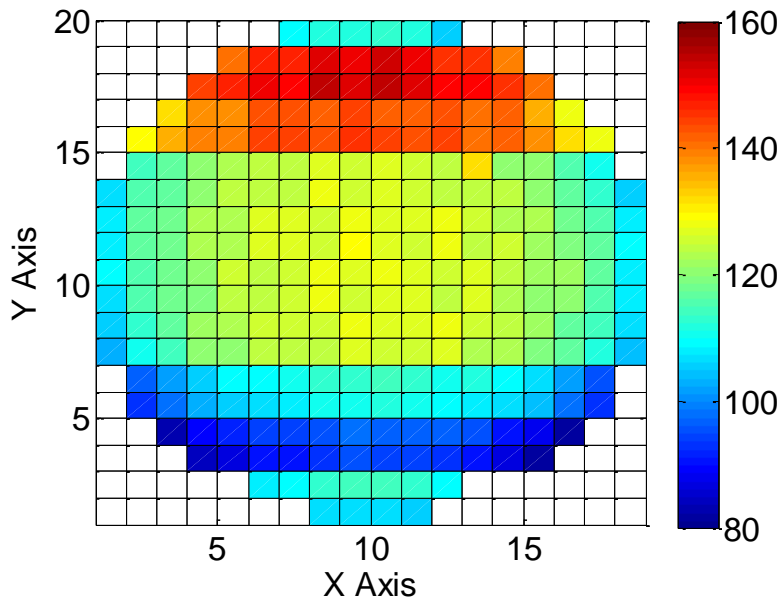
DCT coefficients

$$f(x, y) = \sum_{i=1}^N (b_i(x, y) \cdot \alpha_i)$$

Results in an **under-determined** linear equation, since we have **less** measurements than unknown DCT coefficients

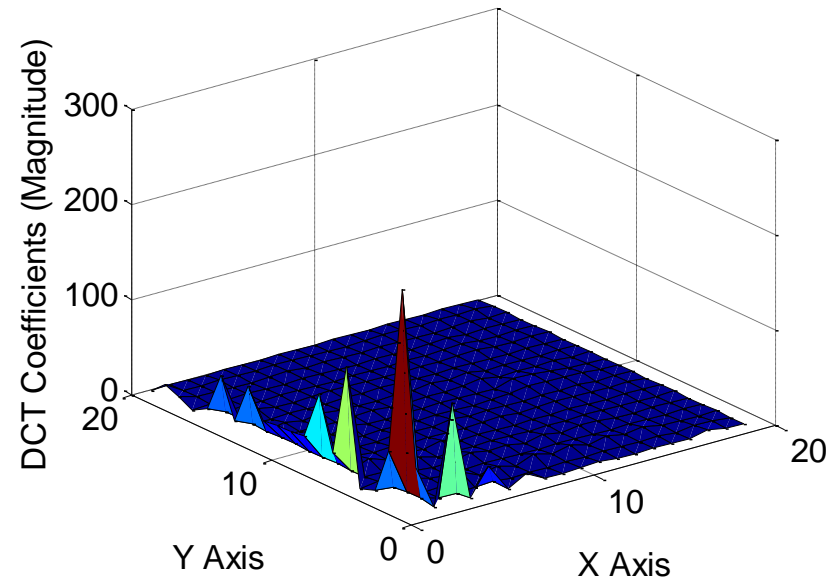
Virtual Probe (VP)

- Additional information is required to uniquely solve under-determined linear equation



Measured delay values (normalized)
from 282 industrial chips

DCT



DCT coefficients (**sparse**)

If process variations are **spatially correlated**
wafer maps show **sparse** patterns in frequency domain

Virtual Probe (VP)

■ Solve sparse DCT coefficients by L1-norm regularization

- ▼ DCT coefficients can be uniquely determined from a small number of measurements

DCT basis function

B

$$\begin{bmatrix} \times \\ \times \\ \times \end{bmatrix} = \begin{bmatrix} \times & \times & \times & \times & \times \\ \times & \times & \times & \times & \times \\ \times & \times & \times & \times & \times \end{bmatrix} \cdot \begin{bmatrix} \times \\ \times \\ \times \\ \times \\ \times \end{bmatrix}$$

Performance measurement
f

DCT coefficients
 α (sparse)

Sum of absolute values of all elements

$$\min_{\alpha} \frac{1}{2} \cdot \|\mathbf{B} \cdot \alpha - \mathbf{f}\|_2^2 + \lambda \cdot \|\alpha\|_1$$

Regularization parameter

Virtual Probe (VP)

Linear regression problem:
$$\min_{\alpha} \frac{1}{2} \cdot \|\mathbf{B} \cdot \alpha - \mathbf{f}\|_2^2 + \lambda \cdot \|\alpha\|_1$$

- There is no closed-form solution
- A standard interior-point solver is not computationally efficient
- We aim to develop an application-specific solver to reduce computational time and, hence, testing cost

Outline

- Motivation and background
 - ▼ Virtual probe (VP)
- **Proposed approach**
 - ▼ Dual Augmented Lagrangian method (DALM)
 - ▼ Two-pass test flow
- **Experimental results**
- **Conclusions**

Dual Problem

Primal problem:
$$\min_{\alpha} \frac{1}{2} \cdot \|\mathbf{B} \cdot \alpha - \mathbf{f}\|_2^2 + \lambda \cdot \|\alpha\|_1$$

- **Key idea: form a dual problem to reduce the number of unknowns**
- **Primal problem**
 - ▼ # of unknowns = # of DCT coefficients \geq # of dies
- **Dual problem**
 - ▼ # of unknowns = # of measurements
- **Since we have substantially less measurements than unknowns, solving the dual problem is significantly more efficient**

Strong Duality

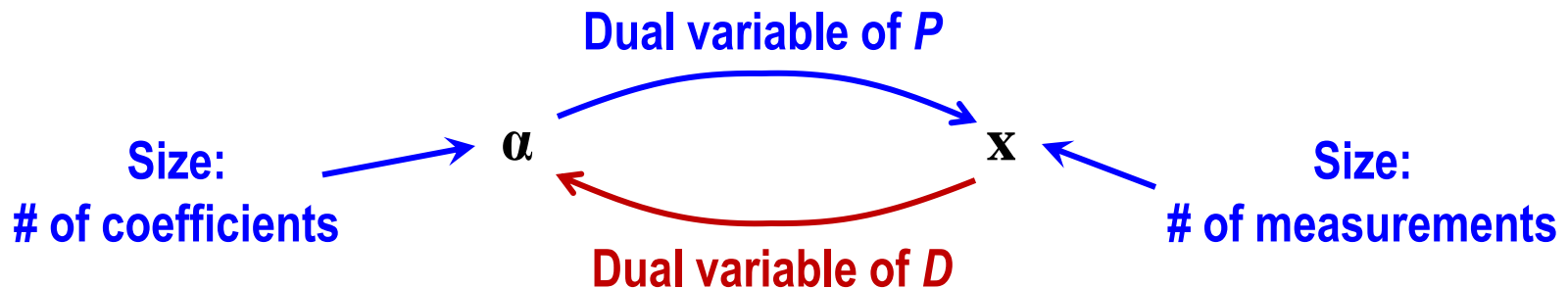
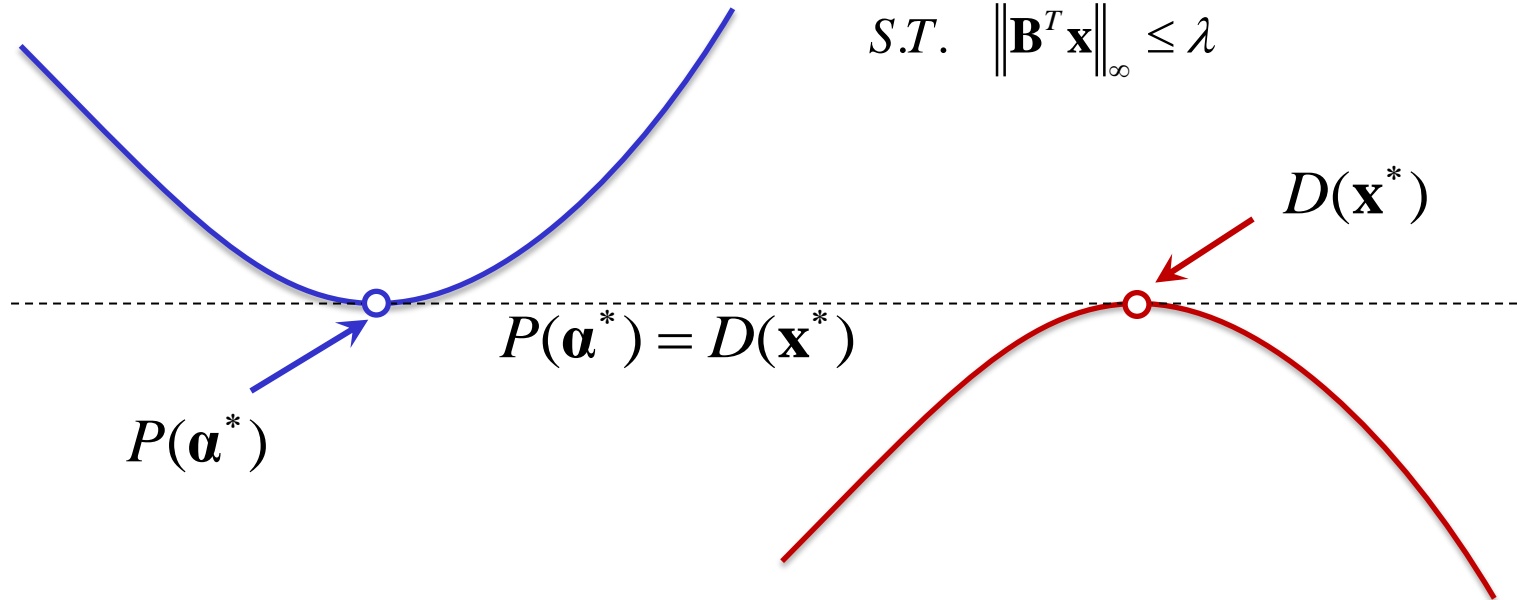
Primal function

$$P(\boldsymbol{\alpha}) = \frac{1}{2} \|\mathbf{B}\boldsymbol{\alpha} - \mathbf{f}\|_2^2 + \lambda \|\boldsymbol{\alpha}\|_1$$

Dual function

$$D(\mathbf{x}) = -\frac{1}{2} \|\mathbf{x} - \mathbf{f}\|_2^2 + \frac{1}{2} \|\mathbf{f}\|_2^2$$

$$S.T. \quad \|\mathbf{B}^T \mathbf{x}\|_\infty \leq \lambda$$

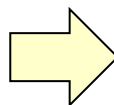


Dual Augmented Lagrangian

- Define an auxiliary variable \mathbf{z} to form an equality constraint

Dual problem

$$\begin{aligned} \max_{\mathbf{x}} \quad & D(\mathbf{x}) = -\frac{1}{2} \|\mathbf{x} - \mathbf{f}\|_2^2 + \frac{1}{2} \|\mathbf{f}\|_2^2 \\ \text{S.T.} \quad & \|\mathbf{B}^T \mathbf{x}\|_\infty \leq \lambda \end{aligned}$$



Dual problem w/ equality constraint

$$\begin{aligned} \max_{\mathbf{x}, \mathbf{z}} \quad & D(\mathbf{x}) = -\frac{1}{2} \|\mathbf{x} - \mathbf{f}\|_2^2 + \frac{1}{2} \|\mathbf{f}\|_2^2 \\ \text{S.T.} \quad & \mathbf{z} = \mathbf{B}^T \mathbf{x} \\ & \|\mathbf{z}\|_\infty \leq \lambda \end{aligned}$$

- Solve the augmented Lagrangian of the dual problem

$$\max_{\mathbf{x}, \mathbf{z}} \quad L_A(\mathbf{x}, \mathbf{z}, \boldsymbol{\alpha}) = -\frac{1}{2} \cdot \|\mathbf{x} - \mathbf{f}\|_2^2 + \frac{1}{2} \cdot \|\mathbf{f}\|_2^2 + \boldsymbol{\alpha}^T \cdot (\mathbf{z} - \mathbf{B}^T \mathbf{x}) - \frac{\eta}{2} \cdot \|\mathbf{z} - \mathbf{B}^T \mathbf{x}\|_2^2 - \delta_\infty^\lambda(\mathbf{z})$$

Primal variable
size = # of DCT coefficients

$$\delta_\infty^\lambda(\mathbf{z}) = \begin{cases} 0 & , \|\mathbf{z}\|_\infty \leq \lambda \\ +\infty & , \|\mathbf{z}\|_\infty > \lambda \end{cases}$$

Alternating Direction Method

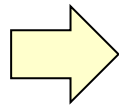
Augmented Lagrangian

$$\max_{\mathbf{x}, \mathbf{z}} L_A(\mathbf{x}, \mathbf{z}, \boldsymbol{\alpha}) = -\frac{1}{2} \cdot \|\mathbf{x} - \mathbf{f}\|_2^2 + \frac{1}{2} \cdot \|\mathbf{f}\|_2^2 + \boldsymbol{\alpha}^T \cdot (\mathbf{z} - \mathbf{B}^T \mathbf{x}) - \frac{\eta}{2} \cdot \|\mathbf{z} - \mathbf{B}^T \mathbf{x}\|_2^2 - \delta_\infty^\lambda(\mathbf{z})$$

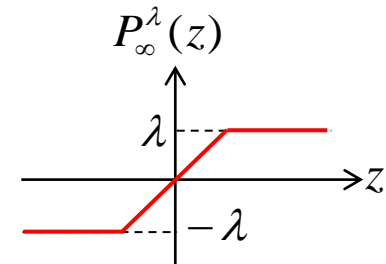
- Solve optimization with alternating direction method [Yang10]

Optimality conditions

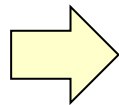
$$\frac{\partial L_A(\mathbf{x}^{(k)}, \mathbf{z}, \boldsymbol{\alpha}^{(k)})}{\partial \mathbf{z}} = 0$$



$$\mathbf{z}^{(k+1)} = P_\infty^\lambda(\boldsymbol{\alpha}^{(k)} / \eta + \mathbf{B}^T \mathbf{x}^{(k)})$$

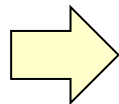


$$\frac{\partial L_A(\mathbf{x}, \mathbf{z}^{(k+1)}, \boldsymbol{\alpha}^{(k)})}{\partial \mathbf{x}} = 0$$



$$\mathbf{x}^{(k+1)} = (\mathbf{I} + \eta \cdot \mathbf{B}\mathbf{B}^T)^{-1} (\mathbf{f} - \mathbf{B}\boldsymbol{\alpha}^{(k)} + \eta \cdot \mathbf{B}\mathbf{z}^{(k+1)})$$

AL step



$$\boldsymbol{\alpha}^{(k+1)} = \boldsymbol{\alpha}^{(k)} + \eta \cdot (\mathbf{B}^T \mathbf{x}^{(k+1)} - \mathbf{z}^{(k+1)})$$

Fast Matrix Inverse

$$\mathbf{x}^{(k+1)} = \underline{(\mathbf{I} + \eta \cdot \mathbf{B}\mathbf{B}^T)^{-1}} (\mathbf{f} - \mathbf{B}\boldsymbol{\alpha}^{(k)} + \eta \cdot \mathbf{B}\mathbf{z}^{(k+1)})$$

- Since DCT basis functions are used, we have

$$\mathbf{B}\mathbf{B}^T = \mathbf{I}$$

- Hence, we do not need to explicitly calculate matrix inverse

$$\mathbf{x}^{(k+1)} = \frac{1}{1 + \eta} \cdot (\mathbf{f} - \mathbf{B}\boldsymbol{\alpha}^{(k)} + \eta \cdot \mathbf{B}\mathbf{z}^{(k+1)})$$

Fast Matrix-Vector Multiplication

$$\mathbf{z}^{(k+1)} = P_\infty^\lambda \left(\alpha^{(k)} / \eta + \underline{\mathbf{B}^T \mathbf{x}^{(k)}} \right)$$

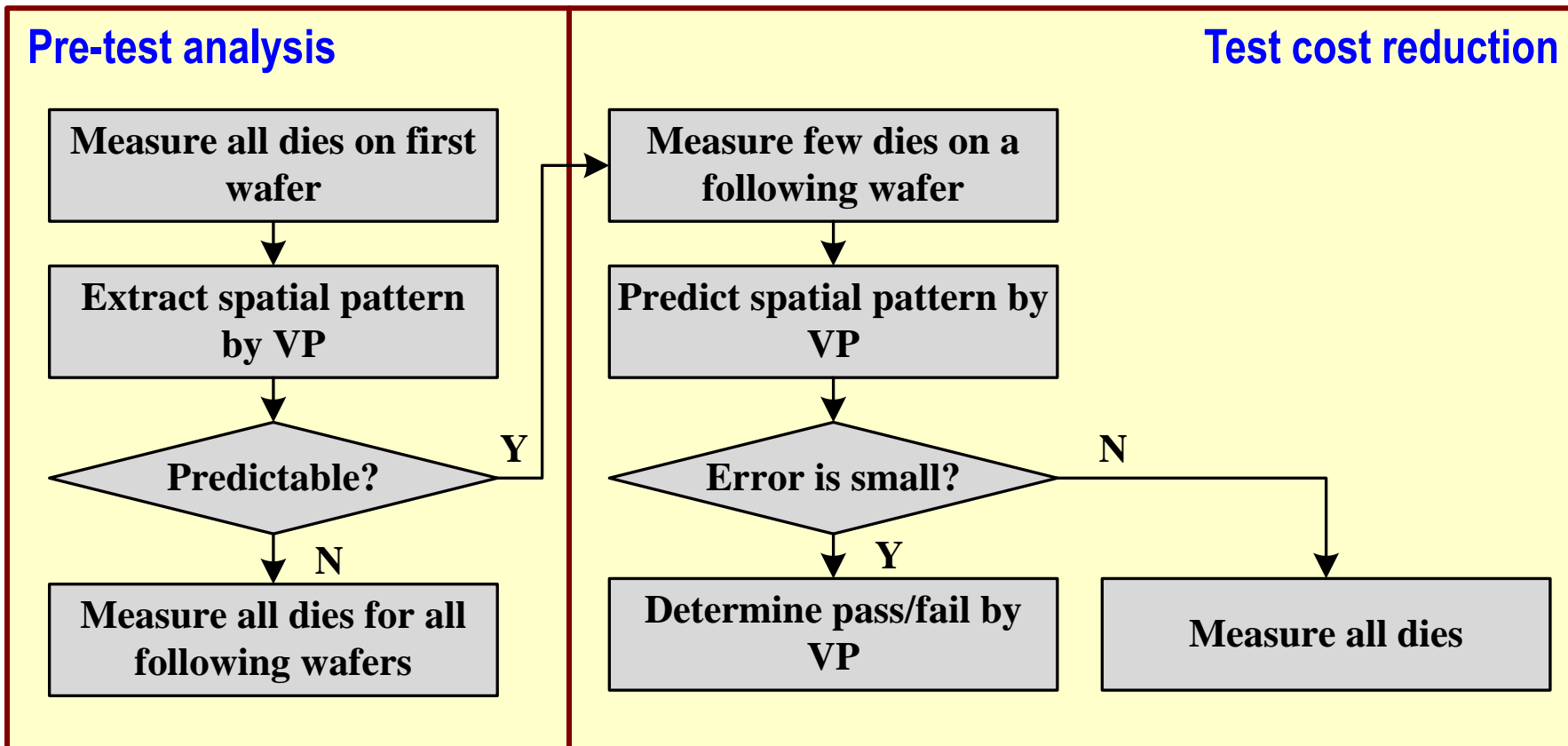
$$\mathbf{x}^{(k+1)} = \frac{1}{1 + \eta} \cdot \left(\mathbf{f} - \underline{\mathbf{B} \alpha^{(k)}} + \eta \cdot \underline{\mathbf{B} \mathbf{z}^{(k+1)}} \right)$$

$$\alpha^{(k+1)} = \alpha^{(k)} + \eta \cdot \left(\underline{\mathbf{B}^T \mathbf{x}^{(k+1)}} - \mathbf{z}^{(k+1)} \right)$$

- Since DCT basis functions are used, we can calculate these matrix-vector multiplications by fast DCT or IDCT transform

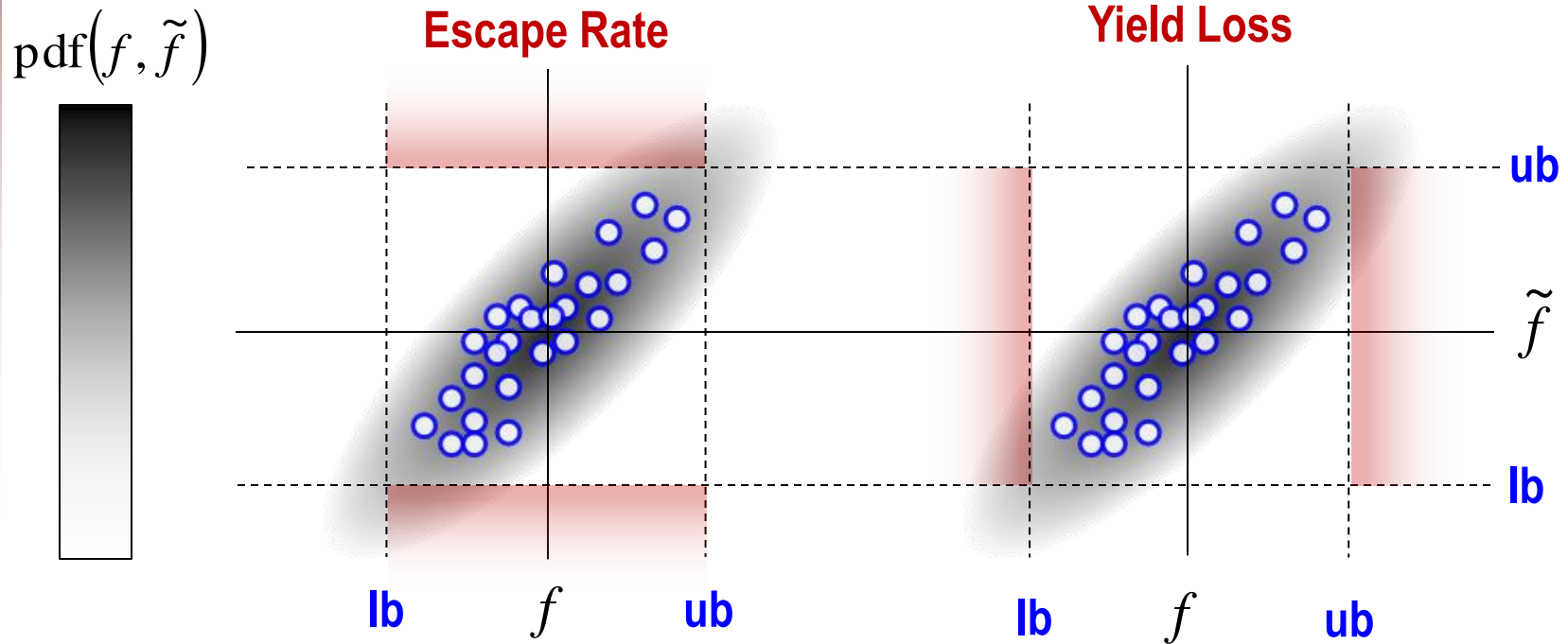
Two-Pass Test Flow

- Measure all dies on one wafer if its spatial pattern cannot be predicted by a number of pre-selected dies



Error Estimation

- Modeling error by VP must be sufficiently small to ensure small escape rate and yield loss



$$ER = \int_{\substack{lb \leq \tilde{f} \leq ub \\ f \geq ub \cup f \leq lb}} \text{pdf}(f, \tilde{f}) \cdot df \cdot d\tilde{f}$$

$$YL = \int_{\substack{lb \leq f \leq ub \\ \tilde{f} \geq ub \cup \tilde{f} \leq lb}} \text{pdf}(f, \tilde{f}) \cdot df \cdot d\tilde{f}$$

\tilde{f} expected values from training f measured values from current wafer

Outline

- Motivation and background
 - ▼ Virtual probe (VP)
- Proposed approach
 - ▼ Dual Augmented Lagrangian method (DALM)
 - ▼ Two-pass test flow
- **Experimental results**
- **Conclusions**

Experimental Setup

■ Production test data of an industrial dual radio RF transceiver

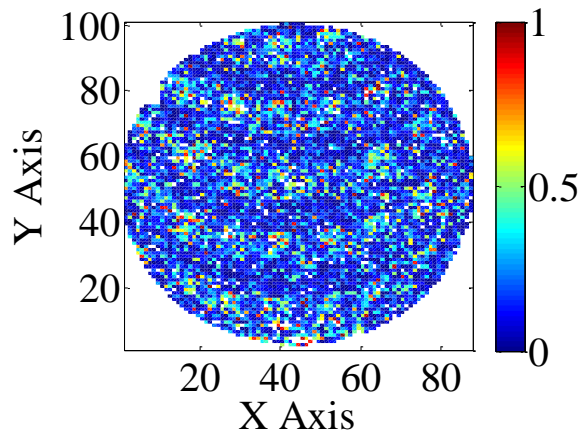
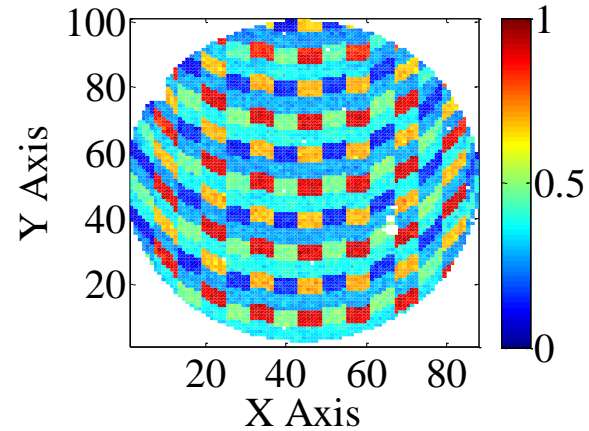
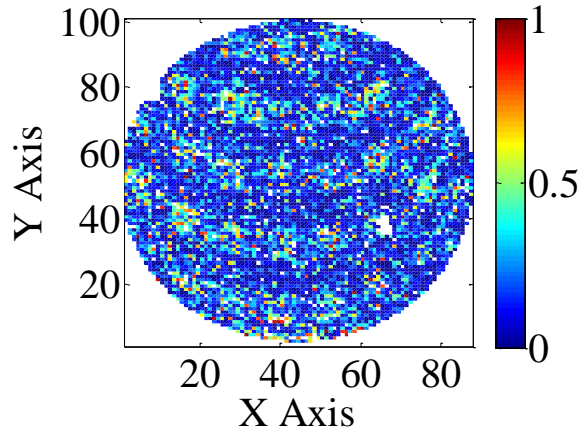
- ▼ 9 lots and 176 wafers in total
- ▼ 6766 dies per wafer and 51 test items per die – test items were selected by [Chang11]
- ▼ 1,089,120 good dies and 101,696 bad dies

Lot ID	1	2	3	4	5	6	7	8	9
Wafer #	25	9	23	25	25	25	17	25	2

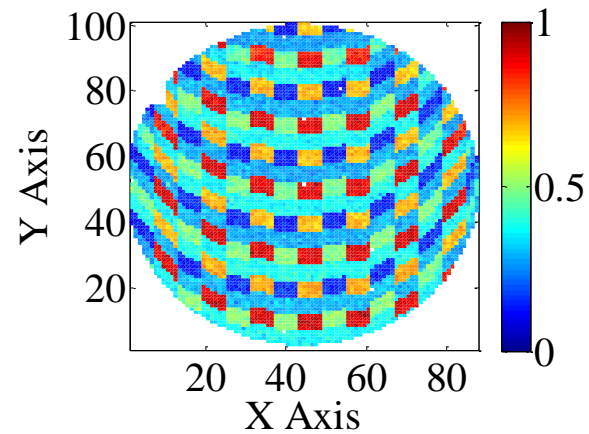
[Chang11]: H. Chang, K. Cheng, W. Zhang, X. Li and K. Butler, “Test cost reduction through performance prediction using virtual probe,” ITC, 2011

Spatial Pattern Examples

- Spatial pattern is observed for a subset of test items, but not all test items



Test item #1



Test item #48

Wafer Map Prediction

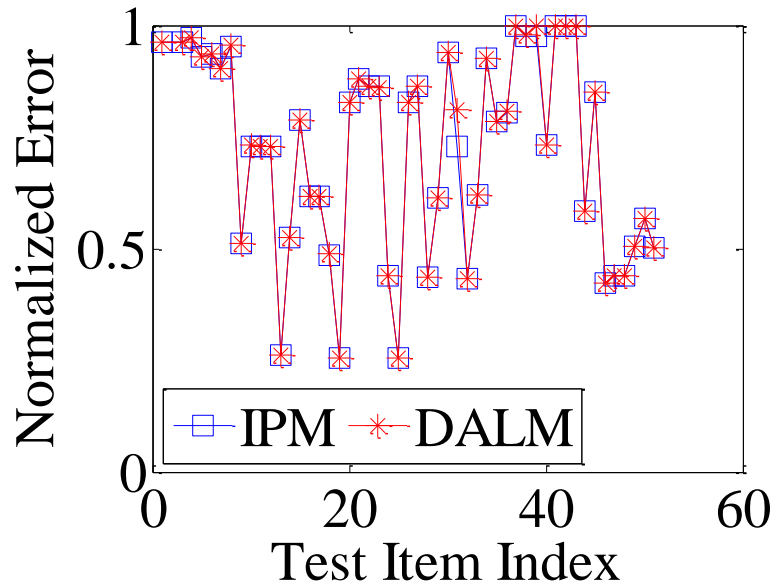
- Two different solvers are implemented for comparison purpose
 - ▼ IPM: interior-point method
 - ▼ DALM: dual augmented Lagrangian method

Number of Dies	IPM	DALM		
	Runtime (Sec.)	Runtime (Sec.)	Iteration #	Speed-up
100	48.3	12.2	7027	3.96×
250	62.7	10.3	5664	6.07×
500	84.7	8.9	5083	9.52×
1000	119.9	8.1	4504	14.88×
2000	171.2	7.3	3922	23.56×
4000	255.2	6.7	3580	37.86×

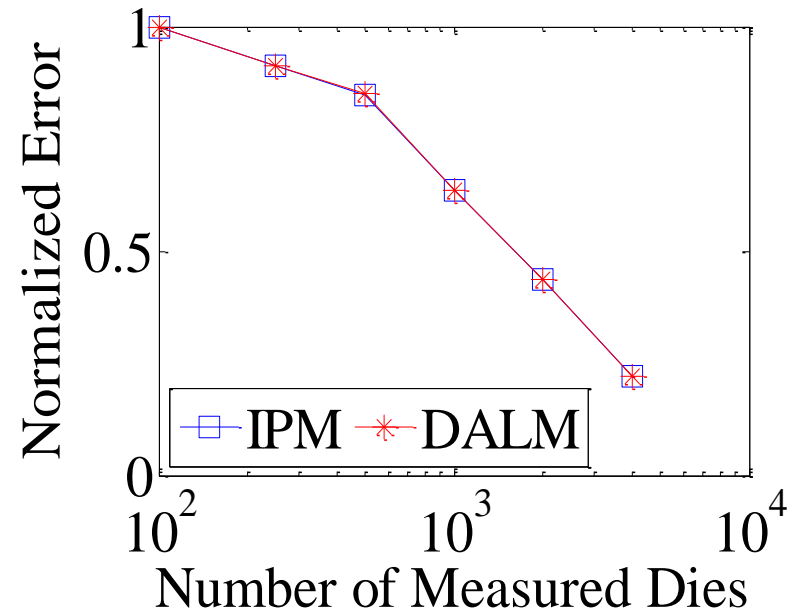
- DALM achieves up to 37× runtime speedup in this example

Wafer Map Prediction

- IPM and DALM result in identical modeling errors



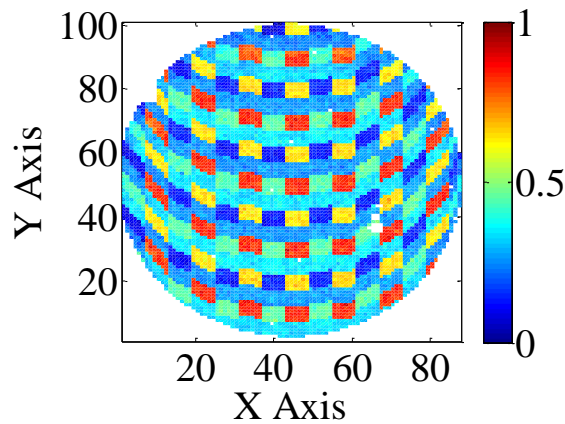
Modeling error with 2000 measured dies per wafer



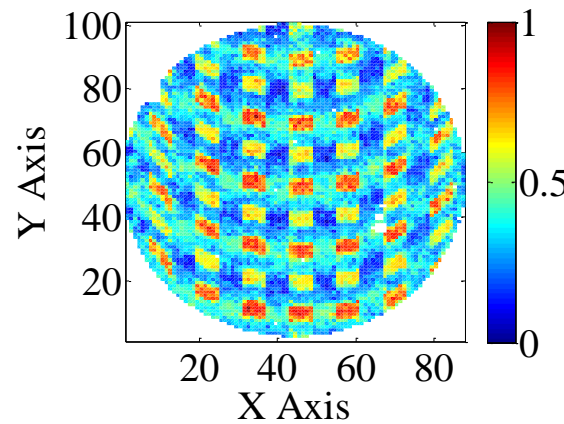
Modeling error for test item #48

Wafer Map Prediction

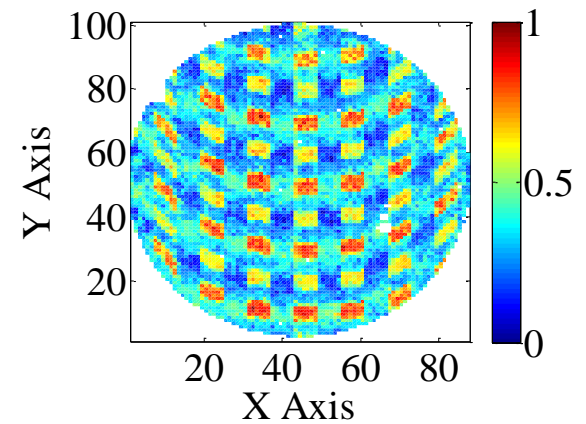
- IPM and DALM predict identical wafer maps



Actual wafer map



Predicted wafer map by IPM

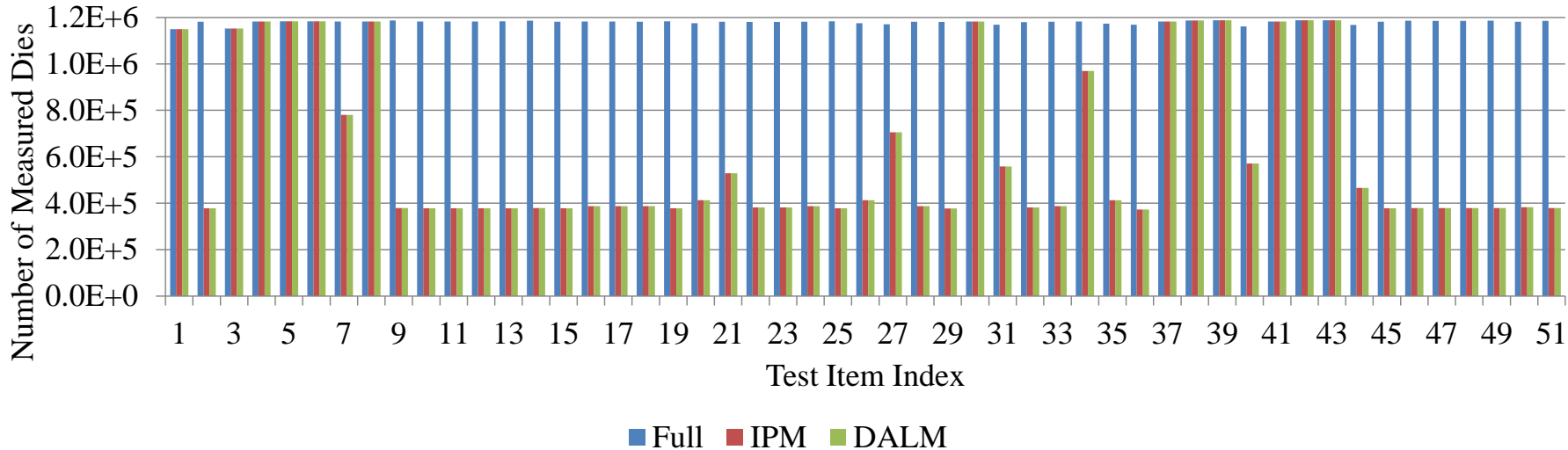


Predicted wafer map by DALM

Test Cost Reduction

■ Total number of measured dies for each test item

▼ IPM and DALM yield identical results



	Full	IPM	DALM
Overall test cost	60M	32M	32M
Test cost reduction	—	1.9×	1.9×
Escape rate	—	1.2×10^{-3}	1.2×10^{-3}
Yield loss	—	2.0×10^{-3}	2.0×10^{-3}

Conclusions

- **Reducing test cost is a critical task for nanoscale integrated circuit design and manufacturing**
 - ▼ Virtual Probe (VP) is an efficient method for test cost reduction based on wafer-level spatial variation modeling
- **Propose an efficient **Dual Augmented Lagrangian method (DALM)** to reduce the computational cost of VP**
 - ▼ Achieve up to 37× runtime reduction over the conventional interior-point solver
- **The proposed DALM solver can be further applied to a number of other analog CAD problems related to sparse approximation**
 - ▼ E.g., analog performance modeling, analog self-healing, etc.

References

- [Chang11]: H. Chang, K. Cheng, W. Zhang, X. Li and K. Butler, “Test cost reduction through performance prediction using virtual probe,” ITC, 2011
- [Kupp12]: N. Kupp, K. Huang, J. Carulli and Y. Makris, “Spatial estimation of wafer measurement parameters using Gaussian process models,” ITC, 2012
- [Huang13]: K. Huang, N. Kupp, J. Carulli and Y. Makris, “Handling discontinuous effects in modeling spatial correlation of wafer-level analog/RF tests,” DATE, 2013
- [Hsu13]: C. Hsu, F. Lin, K. Cheng, W. Zhang, X. Li, J. Carulli and K. Butler, “Test data analytics - exploring spatial and test-item correlations in production test data,” ITC, 2013
- [Yang10]: J. Yang and Y. Zhang, “Alternating direction algorithms for l1-problems in compressive sensing,” Technical Report, TR09-37, Rice University, 2010